# TPD4S014 USB Charger Port Protection Including ESD Protection for all Lines and Over Voltage Protection on $V_{BUS}$

## 1 Features

- Input Voltage Protection at $V_{BUS}$ up to 28 V
- Low Ron nFET Switch
- Supports > 2 A Charging Current
- ESD Performance D+/D–/ID/$V_{BUS}$ Pins:
  - ±15-kV Contact Discharge (IEC 61000-4-2)
  - ±15-kV Air Gap Discharge (IEC 61000-4-2)
- Over Voltage and Under Voltage Lockout Features
- Low Capacitance TVS ESD Clamp for USB2.0 High Speed Data Rate
- Internal 17 ms Startup Delay
- Integrated Input Enable and Status Output Signal
- Thermal Shutdown Feature
- Space Saving SON Package (2 mm × 2 mm)

## 2 Applications

- Cell Phones
- eBook
- Portable Media Players
- Digital Camera

## 3 Description

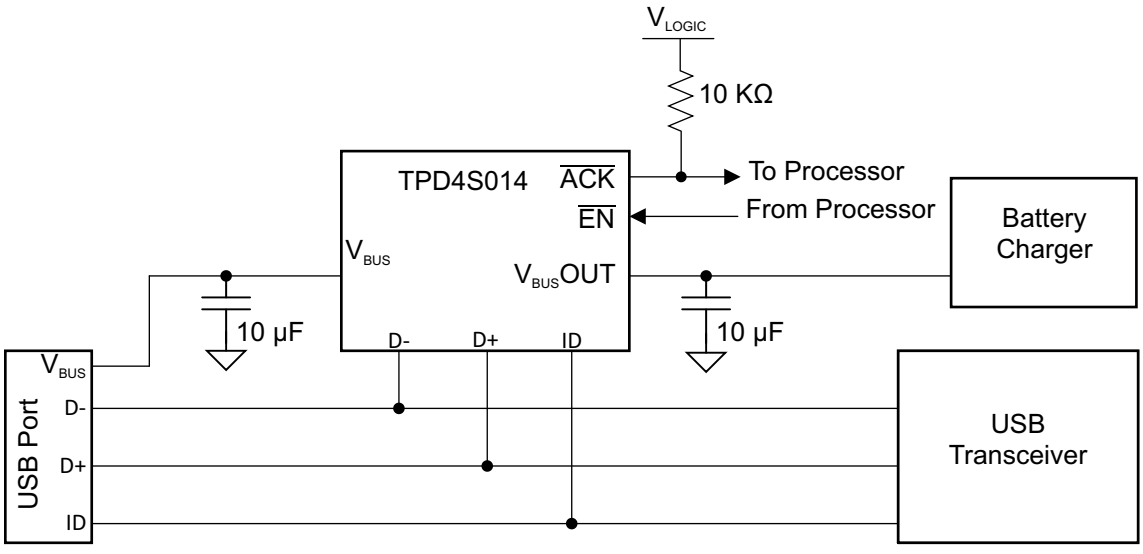
The TPD4S014 is a single-chip solution for USB charger port protection. This device offers low capacitance Transient Voltage Suppressor (TVS) Electrostatic Discharge (ESD) clamps for the D+, D– and standard capacitance for the ID pin. On the $V_{BUS}$ pin, this device provides Over Voltage Protection (OVP) up to 28 V DC. The over voltage lockout feature ensures that if there is a fault condition at the $V_{BUS}$ line, the TPD4S014 is able to isolate the $V_{BUS}$ line to protect the internal circuitry from damage. There is a 17 ms turn-on delay after $V_{BUS}$ rises above the Under Voltage Lockout (UVLO) threshold in order to let the voltage stabilize before turning the nFET on. This function acts as a de-glitch and prevents unnecessary switching if there is any ringing on the line during connection.

**Device Information**[1]

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|---|---|---|
| TPD4S014 | SON (10) | 2.00 mm x 2.00 mm |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

## 4 Simplified Schematic



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## 5 Revision History

**Changes from Revision D (April 2014) to Revision E** — **Page**

- Updated Recommended Operating Conditions table. ... 4
- Changed ... 5
- Updated Electrical Characteristics OVP Circuits table. ... 6
- Changed $t_{ON}$ MAX value from 18 ms to 22ms ... 6
- Changed $t_{OFF}$ 8 µs value from MAX to TYP. ... 6
- Changed $t_{d(OVP)}$ 11 µs value from MAX to TYP. ... 6
- Changed $t_{REC}$ MAX value from 9 ms to 10.5 ms. ... 6
- Updated Application and Implementation section. ... 12

**Changes from Revision C (December 2011) to Revision D** — **Page**

- Added Handling Ratings table. ... 4
- Added Recommended Operating Conditions table. ... 4
- Added Thermal Information table. ... 5
- Updated Electrical Characteristics OVP Circuits table. ... 6

**Changes from Revision B (October 2011) to Revision C** — **Page**

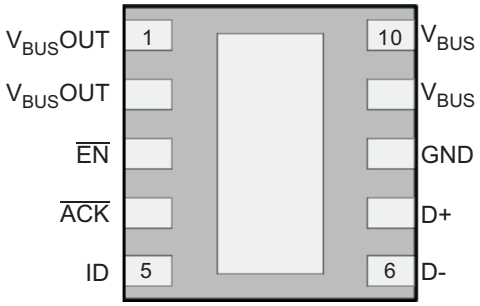
- Made changes to the datasheet to tighten the parameters, VOP+ changed from 5.55V to 5.9V. ... 1
- Updated Description. ... 1

**Changes from Revision A (June 2011) to Revision B** — **Page**

- Changed name of $V_{CC}$ to $V_{BUS}$OUT throughout the entire document. ... 9
- Deleted row from Device Operation table. ... 11
- Added Eye Diagrams to Typical Characteristics section. ... 13

# 6 Pin Configuration and Functions

**10 Pin SON (DSQ) Package**
**(TOP SIDE/SEE-THROUGH VIEW)**




## Pin Functions

| PIN | | TYPE | DESCRIPTION |
|---|---|---|---|
| NAME | NO. | | |
| $V_{BUS}$OUT | 1, 2 | Power Output | Connect to PCB internal PCB plane |
| $\overline{EN}$ | 3 | IO | Enable Active-Low Input. Drive EN low to enable the switch. Drive $\overline{EN}$ high to disable the switch. |
| $\overline{ACK}$ | 4 | I | Open-Drain Adapter-Voltage Indicator Output. $\overline{ACK}$ is driven low after the VIN voltage is stable between UVLO and OVLO for 17 ms (typ). Connect a pullup resistor from $\overline{ACK}$ to the logic I/O voltage of the host system. |
| ID | 5 | IO | ESD-protected line |
| D– | 6 | IO | ESD-protected line |
| D+ | 7 | IO | ESD-protected line |
| GND | 8 | Ground | Ground |
| $V_{BUS}$ | 9, 10 | USB Input Power | Connector Side of $V_{BUS}$ |
| Central PAD | Central PAD | Heat Sink | Electrically disconnected. Use as heat sink. Connect to GND plane via large PCB PAD |

# 7 Specifications

## 7.1 Absolute Maximum Ratings(1)(2)

over operating free-air temperature range (unless otherwise noted)

| | VALUE | | UNIT |
|---|---|---|---|
| | MIN | MAX | |
| Maximum junction temperature | –40 | 150 | °C |
| Max Voltage on $V_{BUS}$ | –0.5 | 30 | V |
| Continuous current through nFET | | 2.6 | A |
| Continuous current through $\overline{ACK}$ | –50 | 50 | mA |
| Max Current through D+, D–, ID, $V_{BUS}$ ESD clamps | | 50 | mA |
| Max voltage on $\overline{EN}$, $\overline{ACK}$, D+, D-, ID, $V_{BUS}$OUT | | 6 | V |

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.

## 7.2 Handling Ratings

| | | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|---|
| $T_{stg}$ | Storage temperature range | | | –65 | 150 | °C |
| $V_{(ESD)}$ | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1) | | –2 | 2 | kV |
| | | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2) | | –1 | 1 | |
| | | IEC 61000-4-2 Contact Discharge | D+, D–, ID, $V_{BUS}$ pins | –15 | 15 | |
| | | IEC 61000-4-2 Air-gap Discharge | D+, D–, ID, $V_{BUS}$ pins | –15 | 15 | |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as ±2 kV may actually have higher performance.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Pins listed as ±1 kV may actually have higher performance.

## 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| $T_A$ | Operating free-air temperature | | –40 | | 85 | °C |
| $V_I$ | Input voltage range | $V_{BUSOUT}$ | –0.1 | | 5.5 | V |
| | | $V_{BUS}$ | –0.1 | | 5.5 | |
| | | $\overline{EN}$ | –0.1 | | 5.5 | |
| | | $\overline{ACK}$ | –0.1 | | 5.5 | |
| | | D+, D-, ID, | –0.1 | | 5.5 | |
| $I_{VBUS}$ | $V_{BUS}$ continuous current(1) | $V_{BUS}$OUT | | | 2.0 | A |
| $C_{VBUS}$ | Capacitance on $V_{BUS}$ | $V_{BUS}$ Pin | | 10 | | µF |
| $C_{VBUS}$OUT | Capacitance on $V_{BUS}$OUT | $V_{BUS}$OUT Pin | | 10 | | µF |
| $R_{\overline{ACK}}$ | Pull up resistor on $\overline{ACK}$ | $\overline{ACK}$ Pin | | 10 | | kΩ |

(1) $IV_{BUS}$ Max value is dependent on ambient temperature. See *Thermal Shutdown* section.

## 7.4 Thermal Information

| THERMAL METRIC[1] | | TPD4S014 DSQ 8 PINS | UNIT |
|---|---|---|---|
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 70.3 | °C/W |
| $R_{\theta JCtop}$ | Junction-to-case (top) thermal resistance | 46.3 | |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 33.8 | |
| $\psi_{JT}$ | Junction-to-top characterization parameter | 2.9 | |
| $\psi_{JB}$ | Junction-to-board characterization parameter | 33.5 | |
| $R_{\theta JCbot}$ | Junction-to-case (bottom) thermal resistance | 16.3 | |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

## 7.5 Electrical Characteristics, $\overline{EN}$, $\overline{ACK}$, D+, D–, ID Pins

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| $V_{IH}$ | High-level input voltage $\overline{EN}$ | Load current = 50 µA | 1 | | | V |
| $V_{IL}$ | Low-level input voltage $\overline{EN}$ | Load current = 50 µA | | | 0.5 | V |
| $I_{LEAK}$ | Input Leakage Current $\overline{EN}$, D+, D–, ID | $V_{IO}$ = 3.3 V | | | 1 | µA |
| $V_{OL}$ | Low-level output voltage $\overline{ACK}$ | $I_{OL}$ = 2 mA | | | 0.1 | V |
| $V_D$ | Diode forward Voltage D+, D–, ID pins; lower clamp diode | $I_O$ = 8 mA | | | 0.95 | V |
| $\Delta C_{IO}$ | Differential Capacitance between the D+, D– lines | | | 0.03 | | pF |
| $C_{IO}$ | Capacitance to GND for the D+, D– lines | | | 1.6 | | pF |
| $C_{IO-ID}$ | Capacitance to GND for the ID line | | | 19 | | pF |
| $V_R$ | Reverse stand-off voltage of D+, D- and ID pins | | | 5 | | V |
| $V_{BR}$ | Breakdown voltage D+, D–, ID pins | $I_{BR}$ = 1 mA | 6 | | | V |
| $V_{BR\ VBUS}$ | Breakdown voltage on $V_{BUS}$ | $I_{BR}$ = 1 mA | 28 | | | V |
| $R_{DYN}$ | Dynamic on resistance D+, D–, ID clamps | $I_I$ = 1 A | | 1 | | Ω |

## 7.6 Electrical Characteristics OVP Circuits

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|---|
| **INPUT UNDERVOLTAGE LOCKOUT** | | | | | | | |
| $V_{UVLO+}$ | Under-voltage lock-out, input power detected threshold rising | | $V_{BUS}$ increasing from 0 V to 5 V, No load on OUT pin | 2.65 | 2.8 | 3 | V |
| $V_{UVLO–}$ | Under-voltage lock-out, input power detected threshold falling | | $V_{BUS}$ decreasing from 5 V to 0 V, No load on OUT pin | 2.25 | 2.44 | 2.7 | V |
| $V_{HYS-UVLO}$ | Hysteresis on UVLO | | Δ of $V_{UVLO+}$ and $V_{UVLO–}$ | 150 | 360 | 550 | mV |
| **INPUT TO OUTPUT CHARACTERISTICS** | | | | | | | |
| $R_{DS\_VBUSSWITCH}$ | $V_{BUS}$ switch resistance | | $V_{BUS}$ = 5 V, $I_{OUT}$ = 500 mA | | 151 | 200 | mΩ |
| $t_{ON}$ | Turn-ON time | | $V_{BUS}$ increasing from 2.8 V to 4.75 V, $\overline{EN}$ = 0 V, $R_L$ = 36 Ω, $C_L$ = 10 uF | 16 | 17.4 | 22 | ms |
| $t_{OFF}$ | Turn-OFF time | | $V_{BUS}$ decreasing from 2.44 V to 0.5 V, $\overline{EN}$ = 0V, $R_L$ = 36 Ω, $C_L$ = 10 uF | | 8 | | µs |
| **INPUT OVERVOLTAGE PROTECTION (OVP)** | | | | | | | |
| $V_{OVP+}$ | Input over –voltage protection threshold rising | $V_{BUS}$ | $V_{BUS}$ increasing from 5 V to 7 V, No Load | 5.9 | 6.15 | 6.45 | V |
| $V_{OVP-}$ | nput over –voltage protection threshold falling | $V_{BUS}$ | $V_{BUS}$ decreasing from 7 V to 5 V, No Load | 5.75 | 5.98 | 6.24 | V |
| $V_{HYS-OVP}$ | Hysteresis on OVP | $V_{BUS}$ | Δ of $V_{OVP+}$ and $V_{OVP–}$ | 25 | 100 | 275 | mV |
| $t_{d(OVP)}$ | Over voltage delay | $V_{BUS}$ | $R_L$ = 36Ω, $C_L$ = 10 µF; $V_{BUS}$ increasing from 5 V to 7 V | | 11 | | µs |
| $t_{REC}$ | Recovery time from input over voltage condition | $V_{BUS}$ | $R_L$ = 36Ω, $C_L$ = 10 µF; $V_{BUS}$ decreasing from 7 V to 5 V | | 8 | 10.5 | ms |

## 7.7 Supply Current Consumption

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | TYP | MAX | UNIT |
|---|---|---|---|---|---|
| $I_{VBUS}$ | $V_{BUS}$ Operating Current Consumption | No load on $V_{BUS\_OUT}$ pin, $V_{BUS}$ = 5 V, $\overline{EN}$ = 0 V | 147.6 | 160 | µA |
| $I_{VBUS\_OFF}$ | $V_{BUS}$ Operating Current Consumption | No load on $V_{BUS\_OUT}$ pin, $V_{BUS}$ = 5 V, $\overline{EN}$ = 5 V | 111.8 | 120 | µA |

## 7.8 Thermal Shutdown Feature

over operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| $T_{SHDN}$ | Thermal Shutdown | | | 144 | | °C |
| $T_{SHDN-HYS}$ | Thermal-Shutdown Hysteresis | | | 23 | | °C |

## 7.9 Typical Characteristics

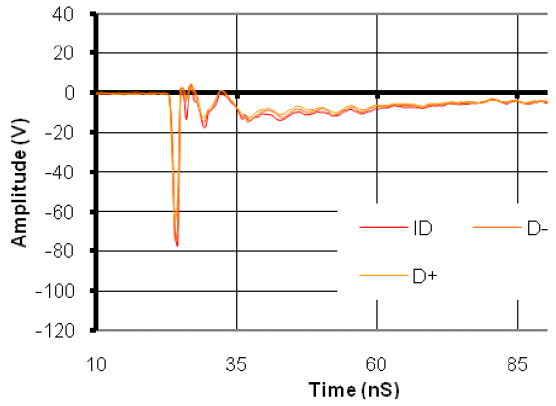



**Figure 1. IEC61000-4-2 -8kV Contact Waveform**

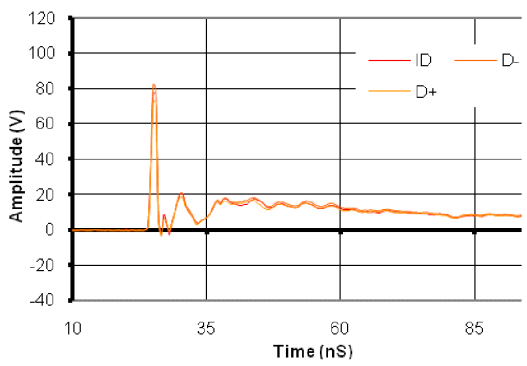



**Figure 2. IEC61000-4-2 +8kV Contact Waveform**

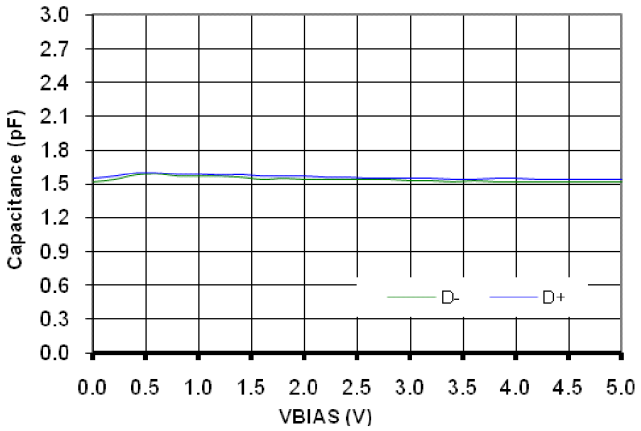



**Figure 3. Capacitance Variation With Voltage**

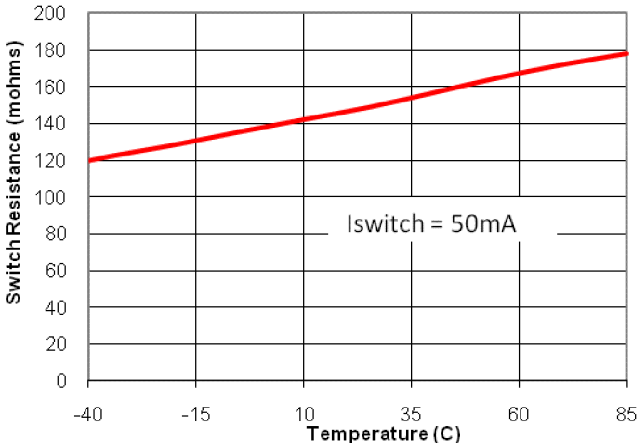



**Figure 4. Variation of On Resistance with Ambient Temperature**

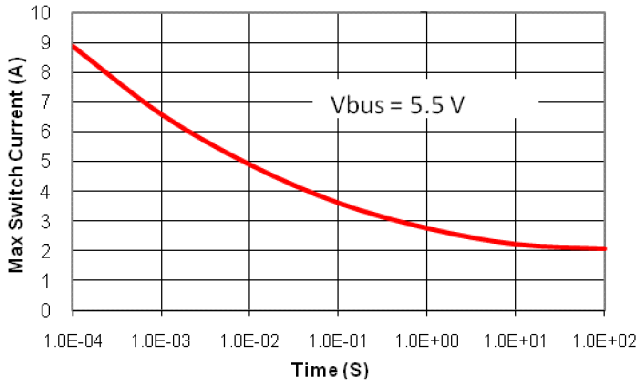



**Figure 5. Max Pulse Current Through Switch vs Pulse Duration**

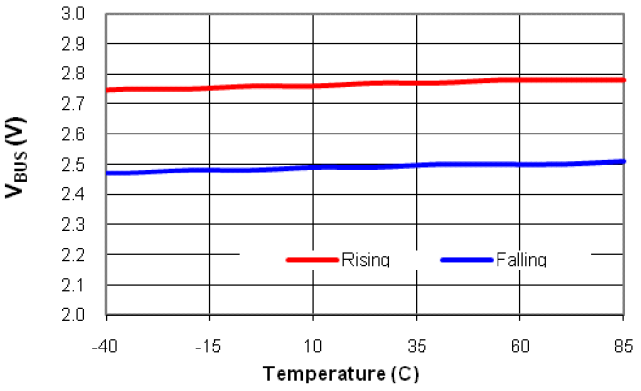



**Figure 6. UVLO Threshold Variation With Temperature**

## Typical Characteristics (continued)

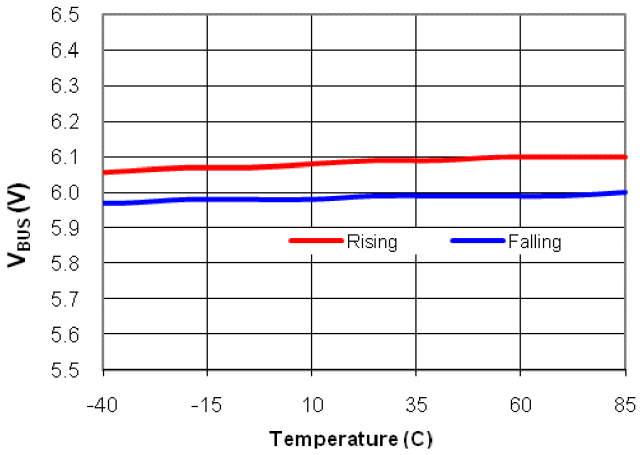



**Figure 7. OVP Threshold Variation With Temperature**

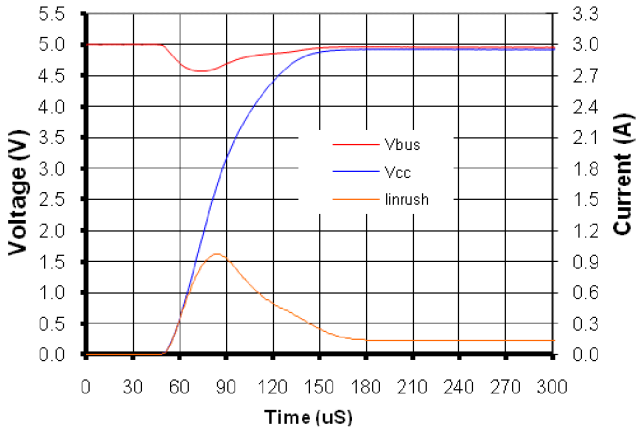



**Figure 8. Start Up Inrush Current Characteristics**

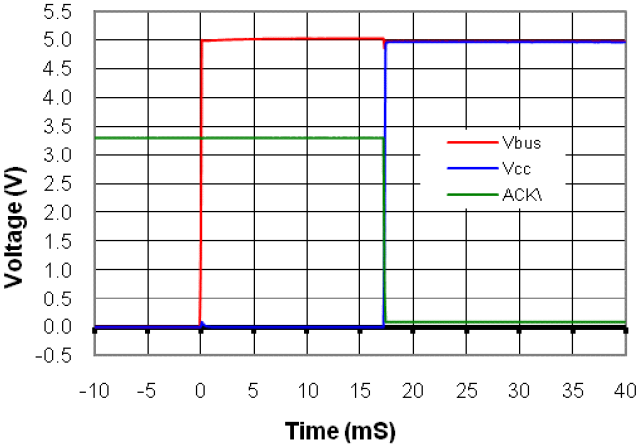



**Figure 9. Device Turn on Characteristics**

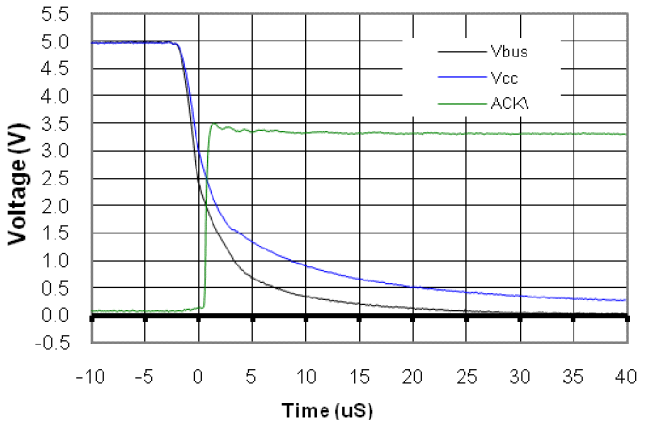



**Figure 10. Device Turn OFF Characteristics (Undervoltage)**

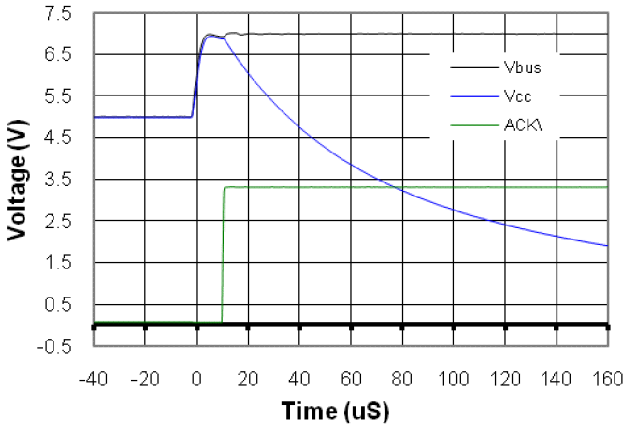


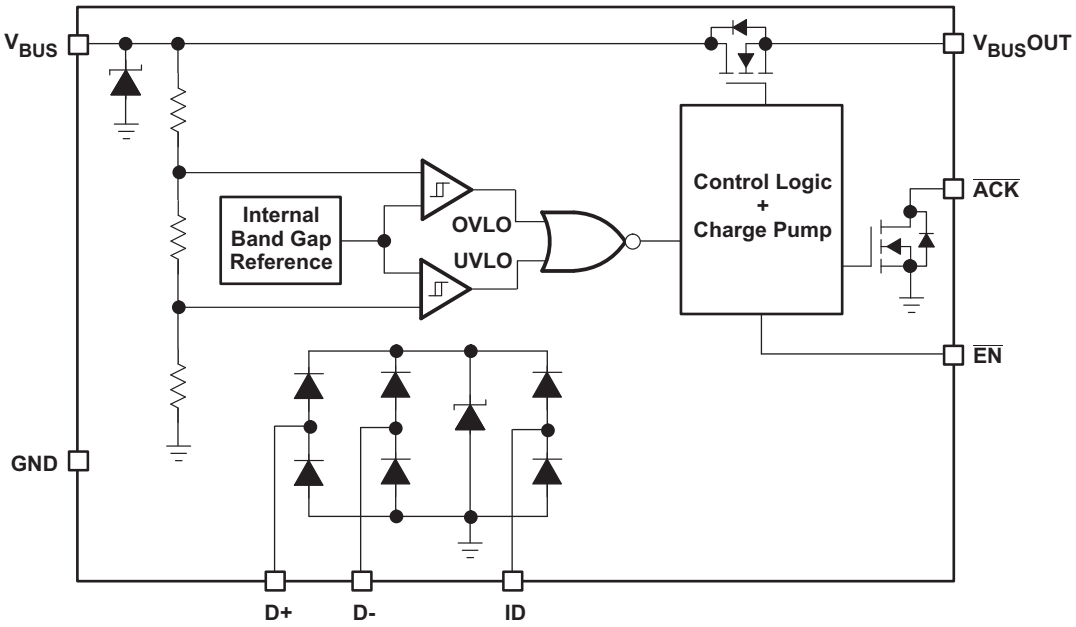

**Figure 11. Device Turn OFF Characteristics (Overvoltage)**

# 8 Detailed Description

## 8.1 Overview

The TPD4S014 provides a single-chip protection solution for USB charger interfaces. The $V_{BUS}$ line is tolerant up to 28 V DC. A Low RON nFET switch is used to disconnect the downstream circuits in case of a fault condition. At power-up, when the voltage on $V_{BUS}$ is rising, the switch will close 17 ms after the input crosses the under voltage threshold, thereby making power available to the downstream circuits. The TPD4S014 also has an $\overline{ACK}$ output, which de-asserts to alert the system a fault has occurred. The TPD4S014 offers 4 channel ESD clamps for D+, D-, ID, and $V_{BUS}$ pins that provide IEC61000-4-2 level 4 ESD protection. This eliminates the need for external TVS clamp circuits in the application.

## 8.2 Functional Block Diagram




## 8.3 Feature Description

### 8.3.1 Input Voltage Protection at $V_{BUS}$ up to 28 V DC

When the input voltage rises above $V_{OVP,}$ or drops below the $V_{UVLO}$, the internal $V_{BUS}$ switch is turned off, removing power to the application. The $\overline{ACK}$ signal is de-asserted when a fault condition is detected. If the fault was an over voltage event, the $V_{BUS}$ nFET switch turns on 8ms ($t_{REC}$) after the input voltage returns below $V_{OVP}$ – $V_{HYS\_OVP}$ and remains above $V_{UVLO.}$ If the fault was an under voltage event, the switch turns on 17 ms after the voltage returns above $V_{UVLO+}$ (similar to start up). When the switch turns on, the $\overline{ACK}$ is asserted once again.

### 8.3.2 Low RON nFET Switch

The nFET switch has a total on resistance ($R_{ON}$) of 151 mΩ. This equates to a voltage drop of less than 31 mV when charging at the maximum 2.0 A current level. Such low RON helps provide maximum potential to the system as provided by an external charger.

### 8.3.3 ESD Performance D+/D–/ID/$V_{BUS}$ Pins

The D+, D–, ID, and $V_{BUS}$ pins can withstand ESD events up to ±15 kV Contact and Air-Gap. An ESD clamp diverts the current to ground.

## Feature Description (continued)

### 8.3.4 Over Voltage and Under Voltage Lockout Features

The over voltage and under voltage lockout feature ensures that if there is a fault condition at the $V_{BUS}$ line, the TPD4S014 is able to isolate the $V_{BUS}$ line and protect the internal circuitry from damage. Due to the body diode of the nFET switch, if there is a short to ground on $V_{BUS}$ the system is expected to limit the current to $V_{BUS}$OUT.

### 8.3.5 Capacitance TVS ESD Clamp for USB2.0 Hi-Speed Data Rate

The D+/D– ESD protection pins have low capacitance so there is no significant impact to the signal integrity of the USB 2.0 Hi-Speed data rate.

### 8.3.6 Start-up Delay

Upon startup, TPD4S014 has a built in startup delay. An internal oscillator controls a charge pump to control the turn-on delay ($t_{ON}$) of the internal nFET switch. The internal oscillator controls the timers that enable the turn-on of the charge pump and sets the state of the open-drain $\overline{ACK}$ output. If $V_{BUS} < V_{UVLO}$ or if $V_{BUS} > V_{OVLO}$, the internal oscillator remains off, thus disabling the charge pump. At any time, if $V_{BUS}$ drops below $V_{UVLO}$ or rises above $V_{OVLO}$, $\overline{ACK}$ is released and the nFET switch is disabled.

### 8.3.7 OVP Glitch Immunity

A 17 ms deglitch time has been introduced into the turn on sequence to ensure that the input supply has stabilized before turning the nFET switch ON. Noise on the $V_{BUS}$ line could turn ON the nFET switch when the fault condition is still active. To avoid this, OVP glitch immunity allows noise on the $V_{BUS}$ line to be rejected. Such a glitch protection circuitry is also introduced in the turn off sequence in order to prevent the switch from turning off for voltage transients. The glitch protection circuitry integrates the glitch over time, allowing the OVP circuitry to trigger faster for larger voltage excursions above the OVP threshold and slower for shorter excursions.

### 8.3.8 Integrated Input Enable and Status Output Signal

External control of the nFET switch is provided by an active low $\overline{EN}$ pin. An $\overline{ACK}$ pin provides output logic to acknowledge $V_{BUS}$ is between UVLO and OVP by asserting low.

### 8.3.9 Thermal Shutdown

When the device is ON, current flowing through the device will cause the device to heat up. Overheating can lead to permanent damage to the device. To prevent this, an over temperature protection has been designed into the device. Whenever the junction temperature exceeds 145ºC, the switch will turn off, thereby limiting the temperature. The $\overline{ACK}$ signal will be asserted for an over temperature event. Once the device cools down to below 120ºC the $\overline{ACK}$ signal will be de-asserted, and the switch will turn on if the EN is active and the $V_{BUS}$ voltage is within the UVLO and OVP thresholds. While the over temperature protection in the device will not kick-in unless the die temperature reaches 145ºC, it is generally recommended that care is taken to keep the junction temperature below 125 ºC. Operation of the device above 125 ºC for extended periods of time can affect the long-term reliability of the part.

The junction temperature of the device can be calculated using below formula:

$$T_j = T_a + P_D \theta_{JA} \quad (1)$$

$T_j$ = Junction temperature

$T_a$ = Ambient temperature

$\theta_{JA}$ = Thermal resistance

$P_D$ = Power Dissipated in device

$$P_D = I^2 R_{on} \quad (2)$$

I = Current through device

$R_{ON}$ = Max on resistance of device

## Feature Description (continued)

### Example

At 2-A continuous current power dissipation is given by:

$$P_D = 2^2 \times 0.2 = 0.8W$$

If the ambient temperature is about 60°C the junction temperature will be:

$$T_j = 60 + (0.8 \times 70.3) = 116.24$$

This implies that, at an ambient temperature of 60ºC, TPD4S014 can pass a continuous 2A without sustaining damage. Conversely, the above calculation can also be used to calculate the total continuous current the TPD4S014 can handle at any given temperature.

## 8.4 Device Functional Modes

| OTP | UVLO | OVLO | $\overline{EN}$ | SW | $\overline{ACK}$ |
|---|---|---|---|---|---|
| X | H | X | X | OFF | H |
| X | X | H | X | OFF | H |
| L | L | L | H | OFF | L |
| L | L | L | L | ON | L |
| H | X | X | X | OFF | H |

OTP = Over temperature protection circuit active
UVLO = Under voltage lock-out circuit active
OVLO = Over voltage lock-out circuit active
SW = Load switch
CP = Charge pump
X = Don't Care
H = True
L = False

# 9 Applications and Implementation

## 9.1 Application Information

The TPD4S014 is a single-chip solution for USB charger port protection. This device offers low capacitance TVS type ESD clamps for the D+, D– and standard capacitance for the ID pin. On the $V_{BUS}$ pin, this device can handle over voltage protection up to 28 V. The over voltage lockout feature ensures that if there is a fault condition at the $V_{BUS}$ line TPD4S014 is able to isolate the $V_{BUS}$ line and protect the internal circuitry from damage. In order to let the voltage stabilize before closing the switch there is a 17 ms turn on delay after $V_{BUS}$ crosses the UVLO threshold. This function acts as a de-glitch which prevents unnecessary switching if there is any ringing on the line during connection. Due to the body diode of the nFET switch, if there is a short to ground on $V_{BUS}$ the system is expected to limit the current to $V_{BUS}$OUT.

## 9.2 Typical Application

### 9.2.1 For Non-OTG USB Systems

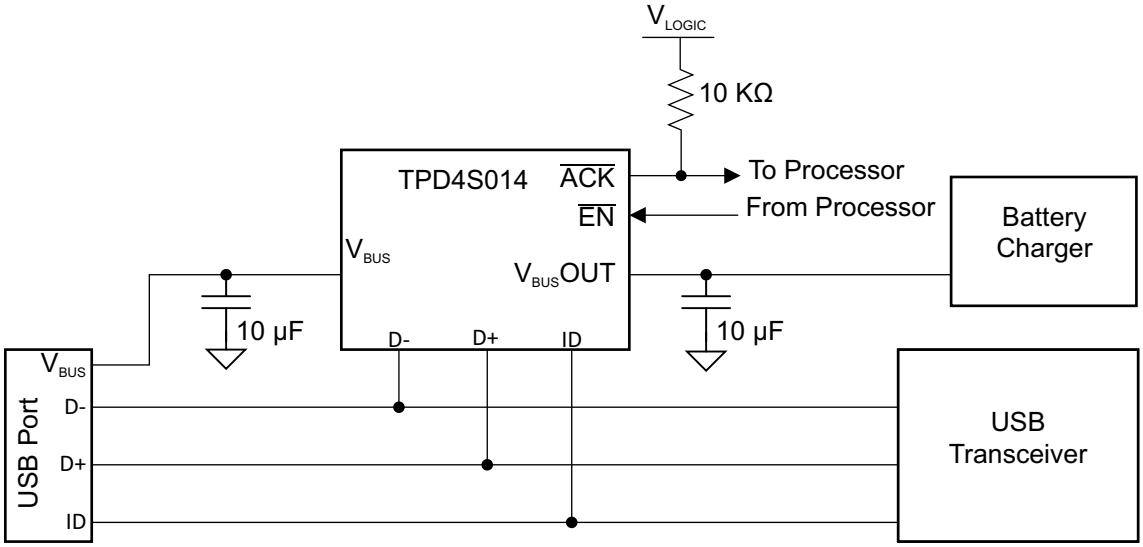



**Figure 12. Non-OTG Schematic**

#### *9.2.1.1 Design Requirements*

| Design Parameters | Example Value |
|---|---|
| Signal range on $V_{BUS}$ | 3.3 V – 5.9 V |
| Signal range on $V_{BUS}$OUT | 3.9 V – 5.9 V |
| Signal range on D+/D– and ID | 0 V – 5 V |
| Drive $\overline{EN}$ low (enabled) | 0 V – 0.5 V |
| Drive $\overline{EN}$ high (disabled) | 1 V – 6 V |

#### *9.2.1.2 Detailed Design Procedure*

To begin the design process, some parameters must be decided upon. The designer needs to know the following:

- $V_{BUS}$ voltage range
- Processor logic levels $V_{OH}$, $V_{OL}$ for $\overline{EN}$ and $V_{IH}$, $V_{IL}$ for $\overline{ACK}$ pins

### 9.2.1.3 Application Curves

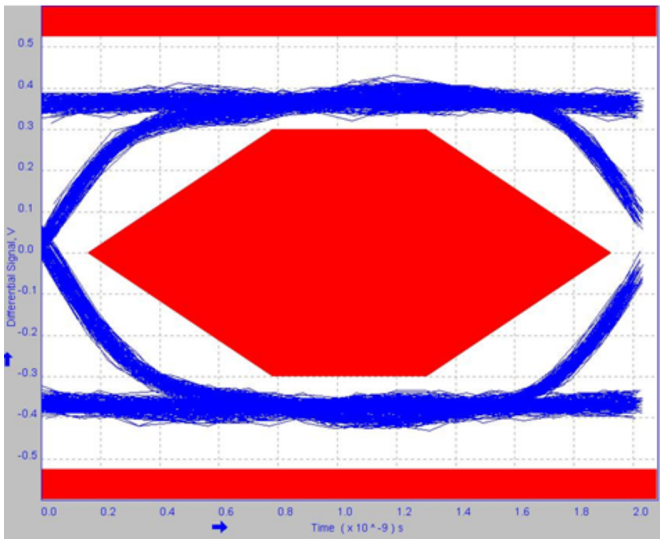



**Figure 13. Eye Diagram With No EVM And No IC, Full USB2.0 Speed At 480Mbps**

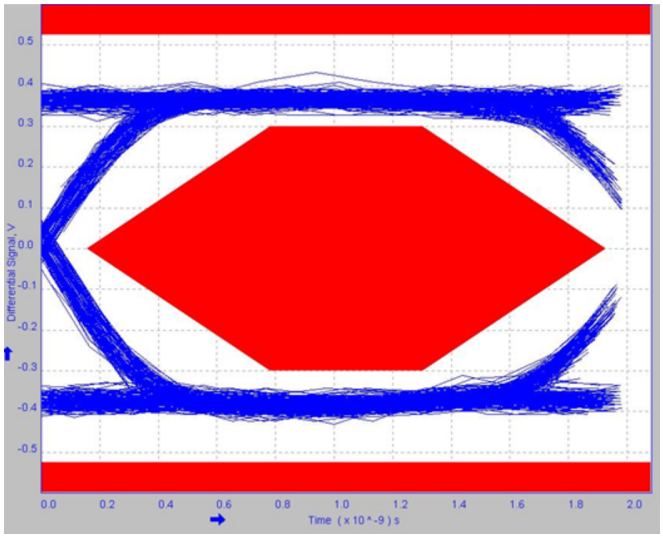



**Figure 14. Eye Diagram With EVM, No IC, Full USB2.0 Speed At 480Mbps**

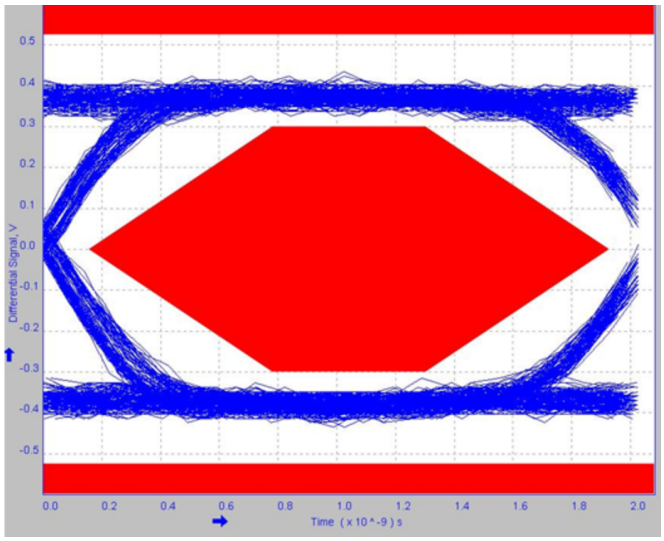



**Figure 15. Eye Diagram With EVM and IC, Full USB2.0 Speed At 480Mbps**

### 9.2.2 For OTG USB Systems

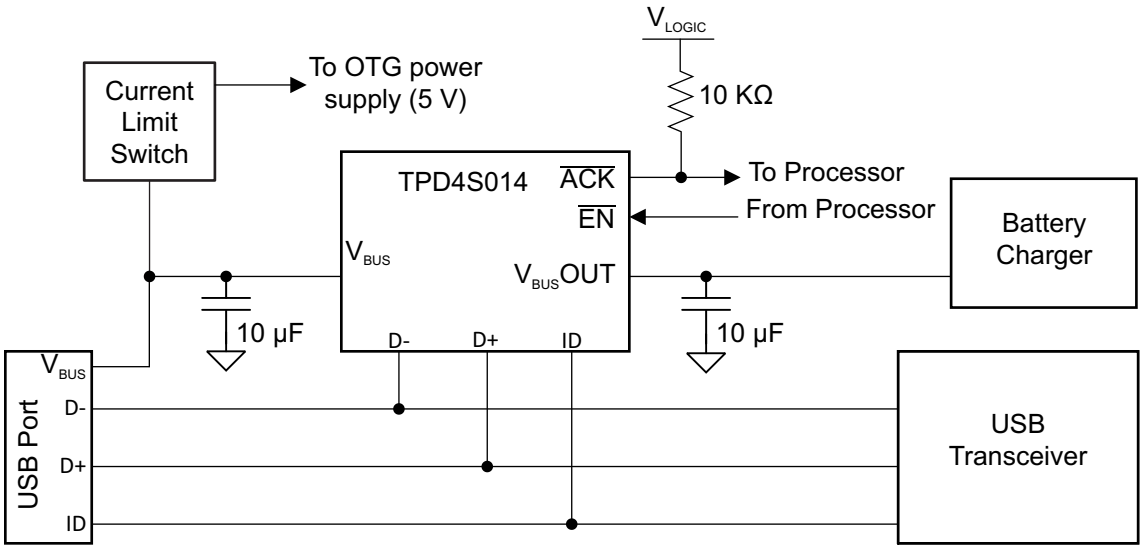



**Figure 16. OTG Schematic**

#### *9.2.2.1 Design Requirements*

| Design Parameters | Example Value |
|---|---|
| Signal range on $V_{BUS}$ | 3.3 V – 5.9 V |
| Signal range on $V_{BUS}OUT$ | 3.9 V – 5.9 V |
| Signal range on D+/D– and ID | 0 V – 5 V |
| Drive $\overline{EN}$ low (enabled) | 0 V – 0.5 V |
| Drive $\overline{EN}$ high (disabled) | 1 V – 6 V |

#### *9.2.2.2 Detailed Design Procedure*

To begin the design process, some parameters must be decided upon. The designer needs to know the following:

- $V_{BUS}$ voltage range
- Processor logic levels $V_{OH}$, $V_{OL}$ for $\overline{EN}$ and $V_{IH}$, $V_{IL}$ for $\overline{ACK}$ pins
- OTG power supply output voltage range

#### *9.2.2.3 Application Curves*

Refer to *Application Curves* in the previous section.

## 10 Power Supply Recommendations

TPD4S014 Is designed to receive power from a USB 3.0 (or lower) $V_{BUS}$ source. It can operate normally (nFET ON) between 3.0 V and 5.9 V. Thus, the power supply (with a ripple of $V_{RIPPLE}$) requirement for TPD4S014 to be able to switch the nFET ON is between 3.0 V + $V_{RIPPLE}$ and 5.9 V – $V_{RIPPLE}$.

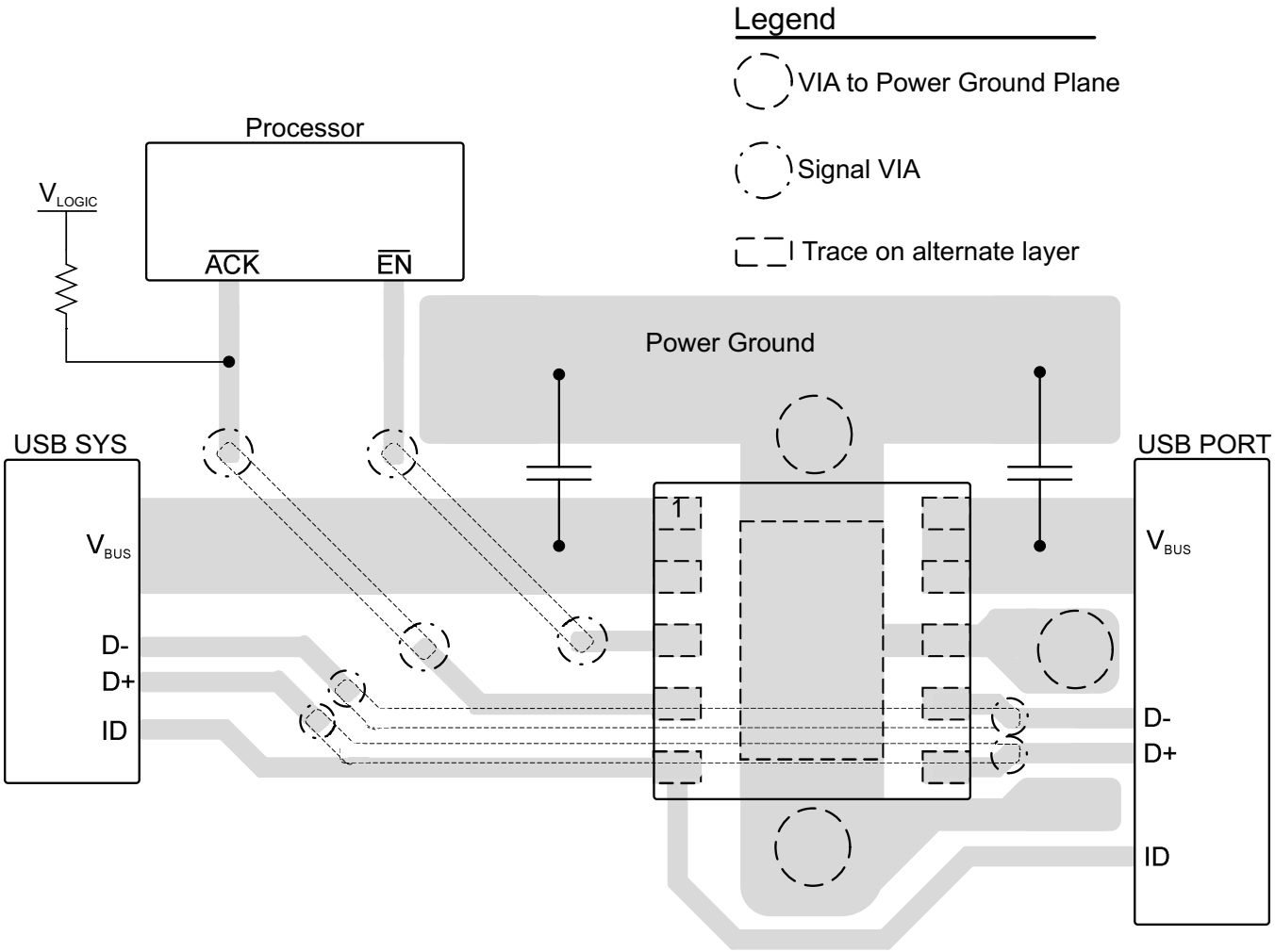
# 11 Layout

## 11.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
  - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
  - The PCB designer needs to minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
  - Keep traces between the connector and TPD4S014 on the same layer as TPD4S014.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
  - Electric fields tend to build up on corners, increasing EMI coupling.

When designing layout for TPD4S014, note that $V_{BUS}$OUT and $V_{BUS}$ pins allow for extra wide traces for good power delivery. In the example shown, these pins are routed with 25 mil (0.64 mm) wide traces. Place the $V_{BUS}$OUT and $V_{BUS}$ capacitors as close to the device pins as possible. Pull $\overline{ACK}$ up to the Processor logic level high with a resistor. Use external and internal ground planes and stitch them together with VIAs as close to the GND pins of TPD4S014 as possible. This allows for a low impedance path to ground so that the device can properly dissipate any ESD events.

## 11.2 Layout Example



# 12 Device and Documentation Support

## 12.1 Trademarks

All trademarks are the property of their respective owners.

## 12.2 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## 12.3 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

# 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| TPD4S014DSQR | ACTIVE | WSON | DSQ | 10 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | ZTE | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

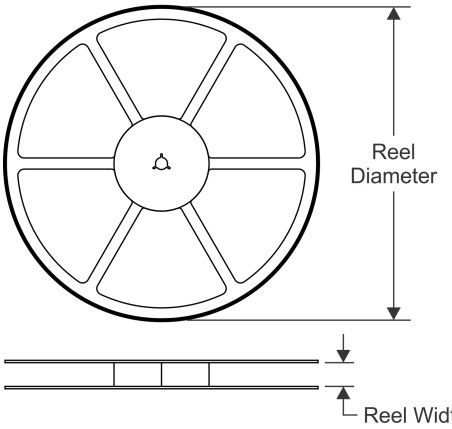
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

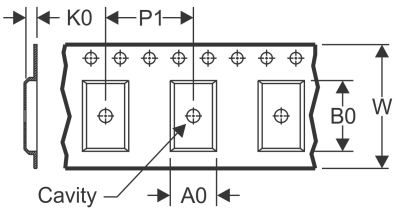
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

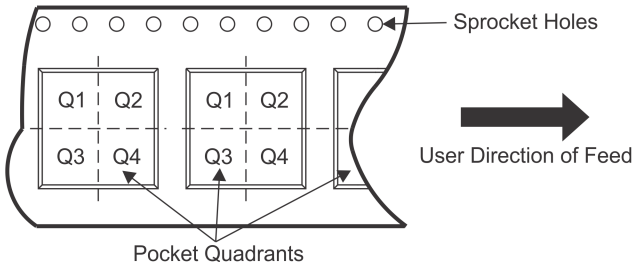



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

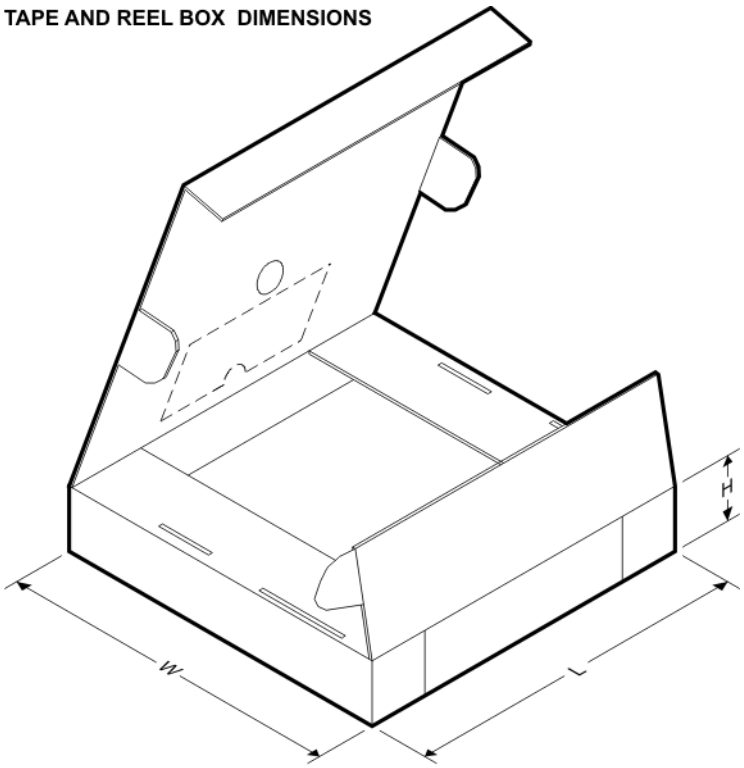
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| TPD4S014DSQR | WSON | DSQ | 10 | 3000 | 179.0 | 8.4 | 2.2 | 2.2 | 1.2 | 4.0 | 8.0 | Q2 |

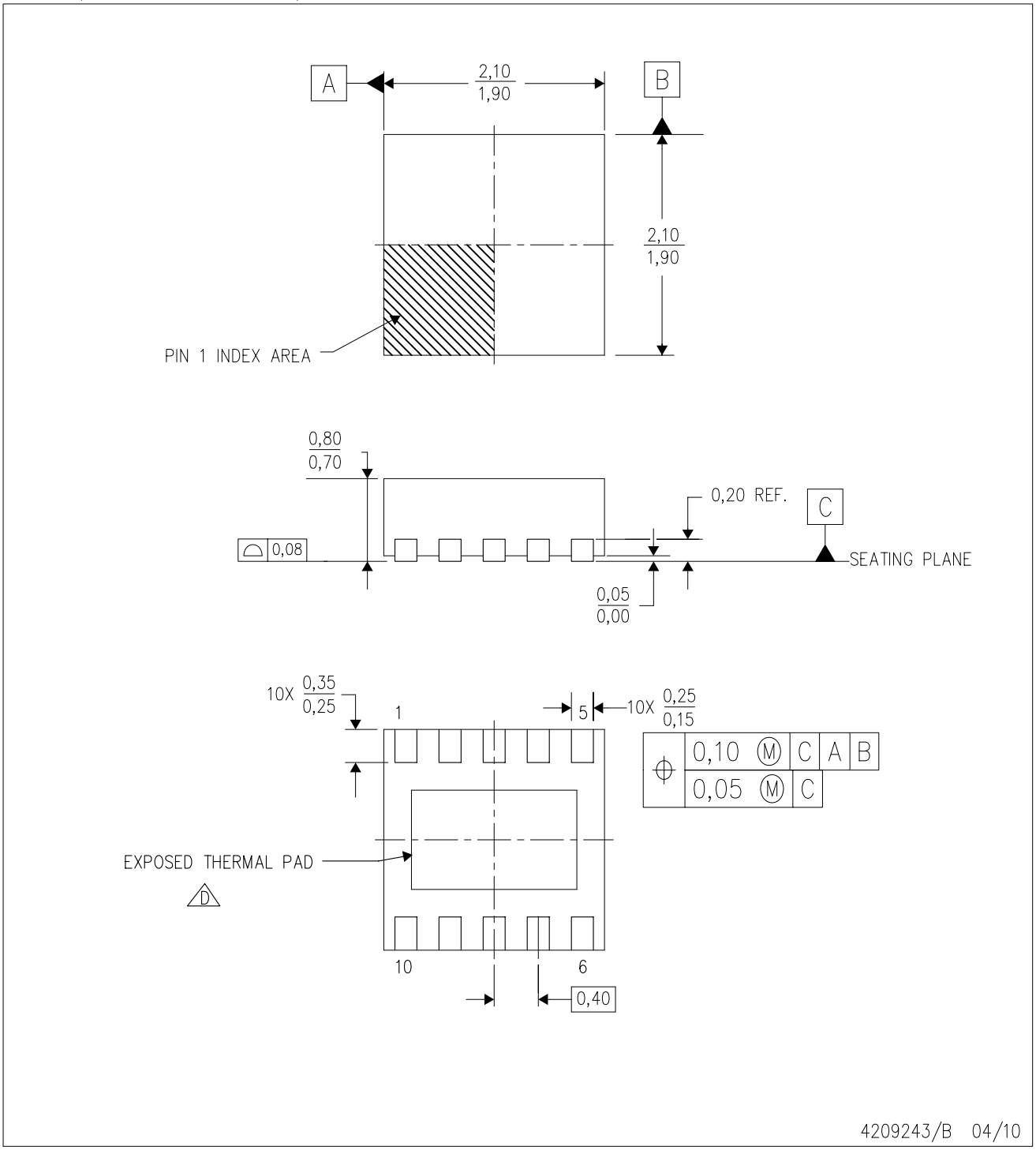
**TAPE AND REEL BOX DIMENSIONS**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| TPD4S014DSQR | WSON | DSQ | 10 | 3000 | 195.0 | 200.0 | 45.0 |

DSQ (S–PWSON–N10) PLASTIC SMALL OUTLINE NO–LEAD




NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Small Outline No–Lead (SON) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.

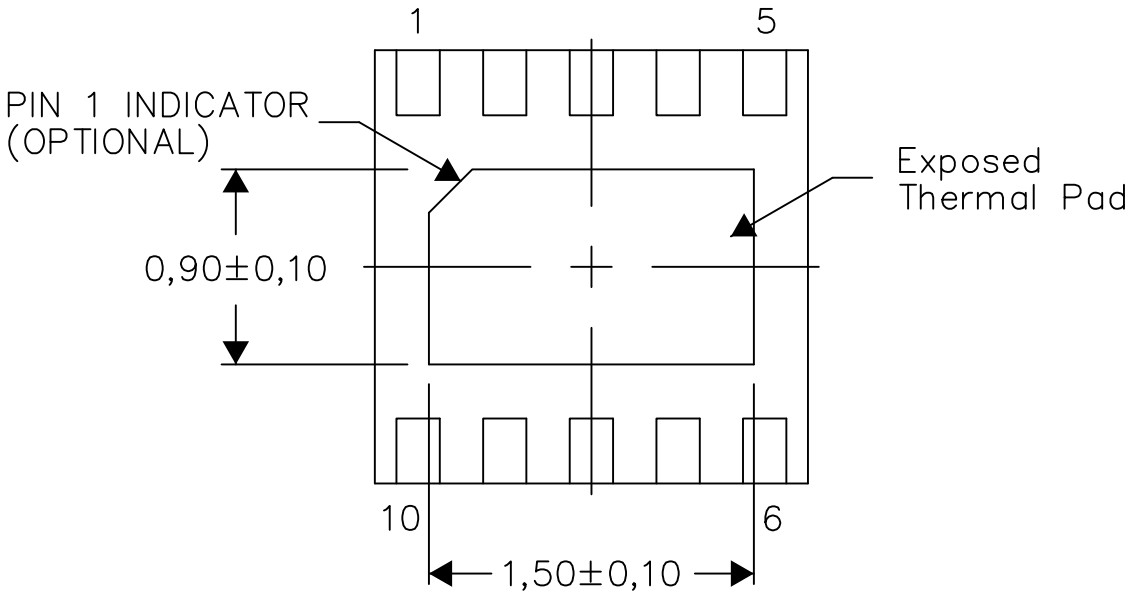
DSQ (R–PWSON–N10) PLASTIC SMALL OUTLINE NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



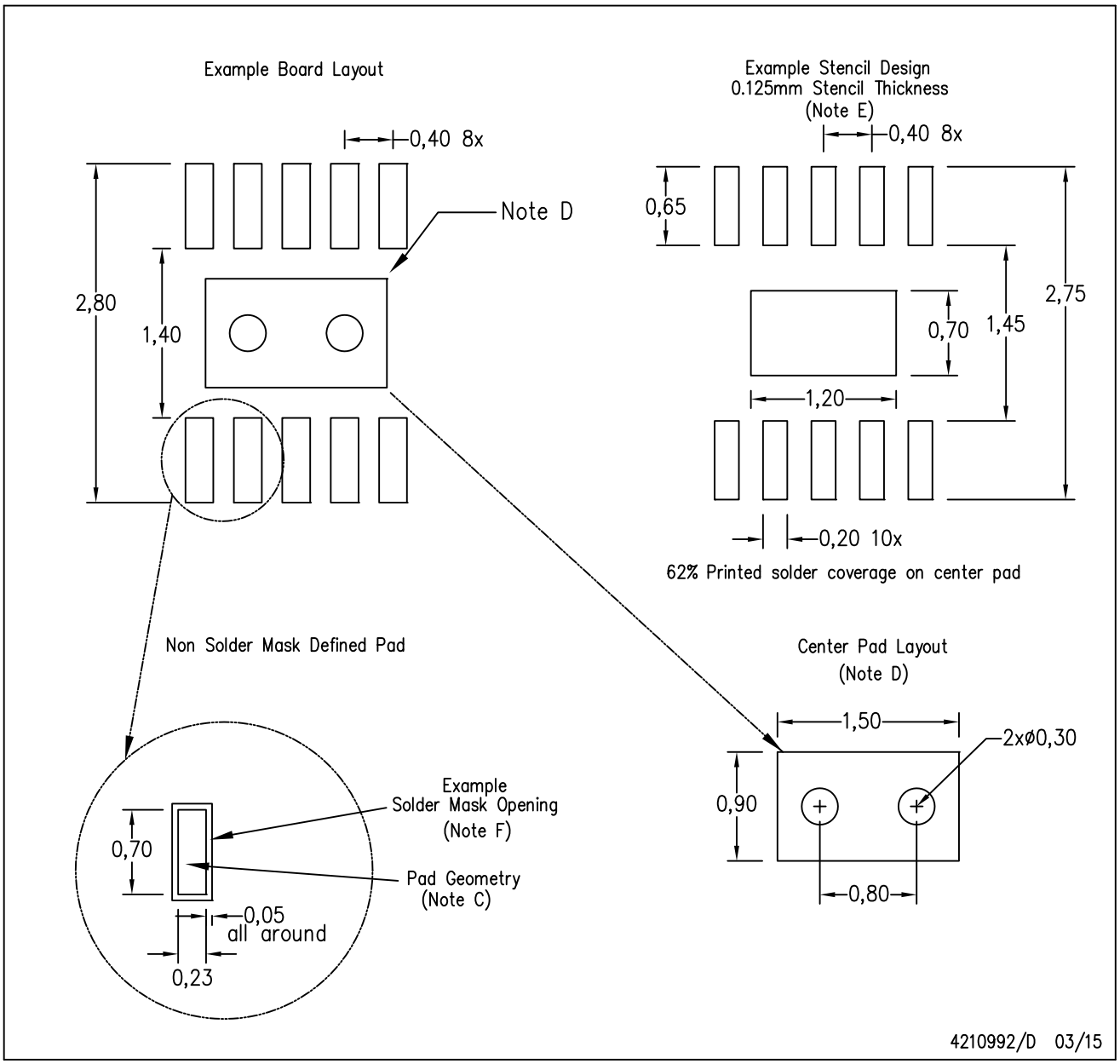

Bottom View

Exposed Thermal Pad Dimensions

4210993/D 03/15

NOTES: A. All linear dimensions are in millimeters

# DSQ (R–PWSON–N10) PLASTIC SMALL OUTLINE NO–LEAD




NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for solder mask tolerances.

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